



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of: **Miwa KOZAWA et al.**

Art Unit: 1756

Application Number: **10/670,291**

Examiner: **Daborah Chacko-Davis**

Filed: **September 26, 2003**

Confirmation Number: **6427**

For: **RESIST PATTERN THICKENING MATERIAL, PROCESS FOR FORMING  
RESIST PATTERN, AND PROCESS FOR MANUFACTURING  
SEMICONDUCTOR DEVICE**

Attorney Docket Number: **031181**

Customer Number: **38834**

**SUBMISSION UNDER 37 C.F.R. §1.114**

Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

February 9, 2009

Sir:

This Submission is being filed concurrently with a Request for Continued Examination pursuant to 37 C.F.R. §1.114.

Amendments to the Claims begin on page 2 of this paper.

Remarks begin on page 11 of this paper.